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Polyolefinic resin composition, useful for shaping general purpose objects, comprises olefinic resin, thermoelastomer and diester compound

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Patent Family

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Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 2001279031	A		6	C08L-023/00	

Abstract:

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NOVELTY A polyolefinic resin composition contains olefinic resin, thermoelastomer and diester compound. The compositions flexibility is controllable.

DETAILED DESCRIPTION A polyolefinic resin composition contains:

- (1) 100 pts. wt. of olefinic resin with melting temperature or softening temperature of up to 150degreesC,
- (2) 15-100 pts. wt. of thermoelastomer, and
- (3) 1-30 weight parts of ester compound of formula $R(EO)_nO(O)CXC(O)O(EO)_mR(I)$.

X=2-12 C alkylene, aromatic or alicyclic dibasic acid residue;

R=optionally same or different each other 1-15 C alkyl;

E=2-4 C alkylene;

m=1-7;

n=0-7.

USE The composition is useful for all purpose applications.